

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	9	("6222967") or ("6164837") or ("6125043") or ("5857049") or ("5661831") or ("5631988") or ("5449312") or ("5420954") or ("4892337").PN.	USPAT; USOCR	OR	OFF	2005/05/17 17:09
S5	1	randle.in. and @pd="19900109"	USPAT; USOCR	OR	OFF	2005/05/17 17:13
S6	2	hahn.in. and @pd="19960312"	USPAT; USOCR	OR	OFF	2005/05/17 17:13
S7	5	("1120673").PN.	EPO; DERWENT	OR	OFF	2005/05/17 17:18
S9	7444	385/14,129-132,143,145.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/07 13:14
S10	7127	S9 and @ad<"20031024"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/07 13:15
S11	1458	S10 and (core\$1 with cladding\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/07 13:15
S12	1458	S10 and (core\$1 with cladding\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/07 13:15
S13	1122	S12 and (cladding\$1 with (waveguide\$1 wave-guide\$1 (wave adj guide\$1)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/07 13:19
S14	69	S13 and (solder\$4 near9 (pad\$1 plate\$1 surfac\$2))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/07 13:20

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S15	69	S13 and (solder\$4 near9 (pad\$1 plate\$1 surfac\$2))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/07 13:47
S16	15	S9 and (VCSEL\$1 with align\$5) same (VCSEL with (waveguide\$1 wave-guide\$1 (wave adj guide\$1)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/07 13:50
S17	24	S9 and (VCSEL\$1 with align\$5) and (VCSEL with (waveguide\$1 wave-guide\$1 (wave adj guide\$1)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/07 13:53
S18	19	S17 and @ad<"20031024"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/07 13:51
S19	106	(VCSEL\$1 with align\$5) and (VCSEL with (waveguide\$1 wave-guide\$1 (wave adj guide\$1))) and @ad<"20031024"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/07 13:54
S20	16	S19 and (solder\$4) and (C4 C-4 C4-joint\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/07 13:54
S21	22	(US-20020073738-\$ or US-20020076158-\$ or US-20020076170-\$ or US-20030103712-\$ or US-20030108269-\$ or US-20030206679-\$ or US-20040001661-\$ or US-20040047539-\$ or US-20040101268-\$ or US-20040218848-\$ or US-20050032384-\$ or US-20050047708-\$).did. or (US-5761350-\$ or US-5898806-\$ or US-6450699-\$ or US-6477284-\$ or US-6603915-\$ or US-6640021-\$ or US-6819836-\$ or US-6832013-\$ or US-6834133-\$ or US-6885788-\$). did.	US-PGPUB; USPAT	OR	OFF	2005/06/08 15:15

S22	8	S21 and (C4 C-4 C4-joint\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/08 15:19
S23	24328	(core\$1 with cladding\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/08 17:11
S24	5653	((contact\$4 solder\$4) near4 (pad\$1 layer\$1)) same cladding\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/08 17:12
S25	11830	(waveguide\$1 wave-guide\$1 (wave adj guide\$1)) same cladding\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/08 17:13
S26	944	(VCSEL\$2 (vertical adj cavity adj surface adj emit\$4 adj laser\$1)) same (waveguide\$1 wave-guide\$1 (wave adj guide\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/08 17:17
S27	2875	(VCSEL\$2 (vertical adj cavity adj surface adj emit\$4 adj laser\$1)) same (electric\$4 electron\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/08 17:17
S28	39	S23 and S24 and S25 and S26 and S27	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/08 17:18
S29	17150	(semiconduct\$4 (semi-conduct\$4)) with (waveguide\$1 (wave adj guide\$1) wave-guide\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/09 09:39

S30	26974	clad\$4 same (((contact metal\$4 conduct\$4) near3 (pad\$1 layer)) electrod\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/09 09:40
S31	3284	S29 and S30	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/09 09:40
S32	2618	S31 and ((laser\$2 VCSEL\$2 LED\$2) same (waveguide\$1 wave-guide\$1 (wave adj guide\$1)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/09 09:42
S33	66	S32 and (passiv\$4 near4 (align\$5 assembl\$5 connect\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/09 09:43
S34	16	(VCSEL\$2 "(VCSEL)") and ((waveguide\$1 wave-guide\$1 (wave adj guide\$1)) same clad\$5) and (clad\$5 with organic\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/09 12:58
S35	57	((waveguide\$1 wave-guide\$1 (wave adj guide\$1)) with clad\$5) and ((clad\$5 with organic\$5) same (benefi\$5 improv\$6 efficien\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/09 12:37
S36	2812	substrate with (flip-chip\$2 chip\$2) with ((thermal temperature\$1) near4 (expansion expand\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/09 13:02
S37	1703	substrate with (flip-chip\$2 chip\$2) with ((thermal temperature\$1) near4 (expansion expand\$4)) with (coefficient)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/09 13:02

S38	463	substrate with (flip-chip\$2 chip\$2) with ((thermal temperature\$1) near4 (expansion expand\$4)) with (coefficient) and ((epoxy near4 (Si\$2 silic\$4 glass\$2)) (thick adj yarn\$1) (s-glass))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/09 13:04
S39	317	substrate\$1 with (flip-chip\$2 chip\$2) with ((thermal temperature\$1) near4 (expansion expand\$4)) with (coefficient) and (((epoxy near4 (Si\$2 silic\$4 glass\$2)) (thick adj yarn\$1) (s-glass)) with substrate\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/09 13:05
S40	35	substrate\$1 with (flip-chip\$2 chip\$2) with ((thermal temperature\$1) near4 (expansion expand\$4)) with (coefficient) and (((epoxy near4 (Si\$2 silic\$4 glass\$2)) (thick adj yarn\$1) (s-glass)) with substrate\$1 with ppm\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/09 13:05
S41	1	("6756680").PN.	USPAT	OR	OFF	2005/11/13 11:50
S42	11	(C4 C-4) with (chip device transceiver) with (waveguide cladding)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/13 11:51
S43	10	S42 and (@ad<"20031024" @rlad<"20031024")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/13 11:51